

# History of Search - Update :

13 pages.  
(2/21/4).

L Number	Hits	Search Text	DB	Time stamp
1	14	342/\$9.cccls. and (ltcc low-temperature adj (cofired co-fired) adj ceramic)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 21:44
2	2	342/\$9.cccls. and (ltcc low-temperature adj (cofired co-fired) adj ceramic).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 22:36
3	643	(333/26).CCLS.	USPAT	2004/02/21 22:37
4	3	863030.ap.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 22:37
5	2	LTCC.ti,ab,clm. and 342/\$9.cccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 22:46
6	3	mmic near12 transceiver.ti,ab,clm. and 455/\$9.cccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 22:47
7	3	863030.ap.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 22:49
-	0	mmic.ti. and transceiver.clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/27 17:11
-	15	mmic.ti. and transceiver	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:12
-	1	mmic.ti. and transceiver and (tuned or tuning)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:13
-	0	mmic.ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:15
-	2	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and (tuned or tuning).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	0	(mmic or microwave adj monolithic).ti. and transceiver.ti,ab,clm. and 438/\$6.cccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	20	(mmic or microwave adj monolithic).ti. and 438/\$6.cccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/14 14:44
-	370	integrated adj circuit adj board.ti.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2002/09/17 12:07

-	7	integrated adj circuit adj board.ti. and integrated adj circuit adj board.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/17 12:08
-	634	(455/73).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
-	147	(257/277).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:25
-	551	(257/728).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:26
-	1978	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:26
-	1325	((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	70	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) and ((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	3233	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or ((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:27
-	221	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or ((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)) and transceiver.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:28
-	4	((mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.) or ((455/73).CCLS.) or ((257/277).CCLS.) or ((257/728).CCLS.)) and transceiver.ti,ab,clm.) and transfer adj tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 16:29
-	2	("5545924").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:13
-	2	("6124636").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14
-	13	"5423080"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14
-	2	("5423080").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 17:14

-	18	(US-5423080-\$ or US-6124636-\$ or US-6424074-\$ or US-6124765-\$ or US-6278337-\$ or US-6278159-\$ or US-5545924-\$ or US-6268779-\$ or US-6073484-\$ or US-6441449-\$ or US-6201728-\$ or US-6257058-\$).did. or (US-20010001224-\$).did. or (EP-712534-\$ or EP-504020-\$ or JP-11214578-\$ or WO-200075762-\$ or WO-200223674-\$).did.	USPAT; US-PGPUB; DERWENT	2002/10/20 17:34
-	1	((US-5423080-\$ or US-6124636-\$ or US-6424074-\$ or US-6124765-\$ or US-6278337-\$ or US-6278159-\$ or US-5545924-\$ or US-6268779-\$ or US-6073484-\$ or US-6441449-\$ or US-6201728-\$ or US-6257058-\$).did. or (US-20010001224-\$).did. or (EP-712534-\$ or EP-504020-\$ or JP-11214578-\$ or WO-200075762-\$ or WO-200223674-\$).did.) and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:35
-	2724	mmic or monolithic adj microwave adj intergated adj circuit and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:35
-	5	(mmic or monolithic adj microwave adj integrated adj circuit) and transfer adj tape	USPAT; US-PGPUB; DERWENT	2002/10/20 17:36
-	19	(US-5451818-\$ or US-6441449-\$ or US-5423080-\$ or US-6124636-\$ or US-5545924-\$ or US-6257058-\$ or US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or US-6424074-\$ or US-6073484-\$ or US-6268779-\$).did. or (US-20010001224-\$).did. or (EP-504020-\$ or JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-200075762-\$).did.	USPAT; US-PGPUB; DERWENT	2002/10/20 19:33
-	8	((US-5451818-\$ or US-6441449-\$ or US-5423080-\$ or US-6124636-\$ or US-5545924-\$ or US-6257058-\$ or US-6278159-\$ or US-6278337-\$ or US-6201728-\$ or US-6124765-\$ or US-6424074-\$ or US-6073484-\$ or US-6268779-\$).did. or (US-20010001224-\$).did. or (EP-504020-\$ or JP-11214578-\$ or EP-712534-\$ or WO-200223674-\$ or WO-200075762-\$).did.) and thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:05
-	18	(monolithic adj microwave or mmic).ti. and ((thick or thickness) same mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:07
-	0	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil near12 base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:08
-	17	(monolithic adj microwave or mmic).ti. and ((thick or thickness) near12 mil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:12
-	25	cte near4 gaas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50
-	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/20 20:50

	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 07:56
	0	("solder near3 MMIC adj chip").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 07:56
	7	solder near3 MMIC adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:12
	3	silver adj epoxy near6 MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:13
	3	silver adj epoxy near12 chip and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:14
	5	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:15
	6	silver adj epoxy near12 (die or chip) and (monolithic adj microwave or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:21
	16	solder near4 preform and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:21
	13	solder near4 preform and MMIC.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:31
	1	(radio-frequency or radio adj frequency or rf) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:34
	1	(radio-frequency or radio adj frequency or rf or kovar) adj (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 08:34
	2	(radio-frequency or radio adj frequency or rf or kovar) near4 (lid or cover) near15 (MMIC or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:03
	158	isolation near3 (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05
	20	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:05

		5	isolation adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:07
		6	(insulation or isolation or insulating or isolating) adj (via or through-hole or through adj hole) and (chip or die).ti,ab,clm. and (mmic or monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:11
		47	isolation adj via.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
		1	isolation adj via.ti,ab,clm. and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:12
		6	isolation adj via.ti,ab,clm. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:17
		1	(isolation adj via or isolation adj trench).ti,ab,clm. and (chip or die) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:18
	3097		mmic and sti or isolation adj trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19
		0	(isolation adj trench or sti) same mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:19
		112	(isolation adj trench or sti) same chip and (integrated adj circuit or ic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:20
		4	(isolation adj trench or sti) and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 09:31
		12	epoxy near1 silver and integrated adj circuit and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:00
		2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01
		2	("5319329").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01
		2	("5239685").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:01

-	2	("5406122").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02
-	2	("5049978").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02
-	2	("6426686").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/21 10:02
-	0	("863030.ap.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11:23
-	3	863030.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 11:46
-	2	("5451818").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:04
-	0	("MMIC.ti,ab,clm. and thick adj film adj capacitor").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:04
-	1	MMIC.ti,ab,clm. and thick adj film adj capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:11
-	0	MMIC.ti,ab,clm. and air near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:12
-	0	MMIC.ti,ab,clm. and (spacing or air) near2 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:13
-	0	MMIC same (spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:15
-	13	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:16
-	0	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver) and (257/\$6.cccls. or 438/\$6.cccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:17
-	2	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver) and (257/\$6.cccls. or 438/\$6.cccls. or 455/\$6.cccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 12:19

	13	(spacing or air) near12 (insulation or isolation or isolate or insulate) near12 (transmit or transmission) near12 (receive or receiver)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:05
	2	488721.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:12
	37	LTCC and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:13
	0	LTCC near12 transfer adj tape and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:13
	4	LTCC and transfer adj tape and MMIC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 13:18
	4	LTCC and transfer adj tape and (monolithic adj microwave adj integrated adj circuit or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 22:42
	7	(low adj temperature adj co-fired adj ceramic or LTCC) and transfer adj tape and (monolithic adj microwave adj integrated adj circuit or MMIC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:43
	170	MMIC.ti,ab,clm. and capacitor same resistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:44
	73	MMIC.ti,ab,clm. and capacitor same resistor.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:44
	5	MMIC.ti,ab,clm. and capacitor same resistor.ti,ab,clm. and transceiver.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 14:45
	1427	((257/277) or (257/728) or (455/73)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:07
	81	((257/277) or (257/728) or (455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:10
	8	((257/277) or (257/728) or (455/73)).CCLS.) and (mmic or monolithic adj microwave adj integrated adj circuit).ti,ab,clm. and transceiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 17:10
	505	(mem or microelectromechanical).ti.	USPAT; US-PGPUB; DERWENT	2003/03/27 19:38
	160	(mem or microelectromechanical).ti.	USPAT	2003/03/27 19:42
	14	((mem or microelectromechanical).ti.) and 257/\$6.ccls.	USPAT	2003/03/27 19:42

-	4	(mem or microelectromechanical).ti. and pixel mmic.ti. 863030.ap. 863030.ap.	USPAT	2003/03/27 19:42
-	80		USPAT	2003/10/26 15:24
-	2		USPAT	2003/10/26 15:24
-	3		USPAT; US-PPGPUB	2003/10/26 15:25
-	353	(257/664).CCLS.	USPAT; US-PPGPUB	2003/10/26 15:30
-	23	(mmic monolithic adj microwave adj intergated adj circuit).ti,ab,clm. and transceiver.ti,ab,clm.	USPAT; US-PPGPUB	2003/10/26 15:53
-	3	863030.ap.	USPAT; US-PPGPUB	2003/10/26 15:53
-	1	"5111199".PN.	USPAT	2003/10/26 15:56
-	1	"5588041".PN.	USPAT	2003/10/26 15:57
-	1	"5422783".PN.	USPAT	2003/10/26 15:57
-	1	"6064341".PN.	USPAT	2003/10/26 15:58
-	1	"6157545".PN.	USPAT	2003/10/26 15:59
-	1	"5512901".PN.	USPAT	2003/10/26 15:59
-	10	(US-5239685-\$ or US-6627992-\$ or US-6594479-\$ or US-6522868-\$ or US-6442374-\$).did. or (US-20030169134-\$ or US-20020171141-\$ or US-20020086655-\$ or US-20020055349-\$ or US-20020030250-\$).did.	USPAT; US-PPGPUB	2003/10/26 16:04
-	39	(US-5423080-\$ or US-6441449-\$ or US-5406122-\$ or US-6424074-\$ or US-6278159-\$ or US-6278337-\$ or US-6257058-\$ or US-6268779-\$ or US-6124765-\$ or US-6201728-\$ or US-6073484-\$ or US-5451818-\$ or US-6124636-\$ or US-5545924-\$ or US-6498551-\$ or US-6507110-\$ or US-6522868-\$ or US-6476463-\$ or US-6442374-\$ or US-6072991-\$ or US-6627992-\$ or US-6594479-\$ or US-5111199-\$ or US-5422783-\$ or US-5239685-\$ or US-5319329-\$).did. or (US-20010001224-\$ or US-20020030250-\$ or US-20030169134-\$ or US-20020086655-\$ or US-20020055349-\$ or US-20020171141-\$).did. or (EP-504020-\$ or US-5451818-\$ or US-5239685-\$ or WO-200075762-\$ or WO-200223674-\$ or JP-11214578-\$ or EP-712534-\$).did.	USPAT; US-PPGPUB; DERWENT	2003/10/26 16:22
-	1	("5451818").PN.	USPAT	2003/10/26 16:22
-	203	(controlled adj firing co-fired) near12 (multi-layered multi-layer multilayer multilayered) near12 ceramic	USPAT	2003/10/27 08:58
-	161	(controlled adj firing co-fired) near6 (multi-layered multi-layer multilayer multilayered) near6 ceramic	USPAT	2003/10/27 09:22
-	30	(controlled adj firing co-fired) near6 (multi-layered multi-layer multilayer multilayered) near6 ceramic.ti,ab,clm.	USPAT	2003/10/27 10:36
-	8	green adj tape and (mmic monolithic adj microwave adj intergated adj circuit).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 11:43
-	14	millimeter and transceiver and (monolithic mmic) and (green adj tape co-fired co-firing controlled adj firing) near12 ceramic	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:28
-	60	millimeter and transceiver and (monolithic mmic) and ceramic	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:33

	1	millimeter and transceiver and (monolithic mmic) and ceramic and 455/73.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:36
	286	455/\$9.ccls. and (monolithic adj microwave mmic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:37
	73	455/\$9.ccls. and (monolithic adj microwave mmic) and transceiver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:37
	758	455/73.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:37
	13	455/73.ccls. and transceiver and (mmic microwave adj monolithic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 13:41
	412	(455/73).CCLS.	USPAT; US-PGPUB	2003/10/27 14:10
	514	343/700	USPAT; US-PGPUB	2003/10/27 14:11
	15	transfer adj tape and (millimeter adj wave mm adj wave monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 18:39
	3	863030.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 18:25
	416	(333/247).CCLS.	USPAT; US-PGPUB	2003/10/27 18:41
	5	((333/247).CCLS.) and (transfer adj tape ceramic) and transceiver and (mmic monolithic adj microwave millimeter adj wave)	USPAT; US-PGPUB	2003/10/27 20:21
	11	watanabe.in. and (microwave millimeter) and package and "chips"	USPAT; US-PGPUB	2003/10/27 20:22
	11	watanabe.in. and (microwave millimeter) and package and "chips"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 20:22
	3	863030.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 09:02
	28	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) near6 high adj temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 09:13
	3272	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and GHz	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 09:13
	184	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 09:13

-	32	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz and mmic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:14
-	9	(green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz and mmic.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:20
-	666	(333/26).CCLS.	USPAT; US-PGPUB	2003/10/28 09:20
-	1	((333/26).CCLS.) and (green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and ("20" "30") near2 GHz and mmic.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:21
-	9	((green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and "20" near2 GHz and mmic.ti,ab,clm.) and (green adj tape lttt ltcc low adj temperature transfer adj tape low adj temperature adj (cofired co adj fired) adj ceramic) and ("20" "30") near2 GHz and mmic.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:44
-	0	multiple adj MMIC adj chips near6 single adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:45
-	0	(plurality multiple) adj MMIC adj chips near6 single adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:45
-	44	(plurality multiple) adj "chips" near6 single adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:45
-	0	(plurality multiple) adj "chips" near6 single adj substrate and mmic.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:45
-	0	(plurality multiple) adj "chips" near6 single adj substrate and (monolithic mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:46
-	0	(plurality multiple) adj "chips" near6 single adj substrate and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:46
-	29	"chips" near6 single adj substrate and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:46
-	19	"chips" near3 single adj substrate and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 10:20
-	0	"chips" near3 single adj substrate near6 ceramic and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 09:56

-	0	"chips" near3 single adj substrate near6 (transfer adj tape ceramic) and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 09:56
-	47	"chips" near3 ceramic adj substrate and (monolithic microwave millimeter adj wave mmic).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:28
-	0	plurality near2 mmic near2 chips near6 substrate adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:29
-	0	plurality near2 (mmic chips) near6 substrate adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:42
-	13	(mmic "chips") near6 substrate adj board and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:45
-	8	"chips" near6 substrate adj board and ceramic and (mmic monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:53
-	8	"chips" near6 substrate adj board and ceramic and (mmic monolithic adj microwave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 10:54
-	384	(333/247).CCLS.	USPAT	2003/10/28 10:54
-	28	((333/247).CCLS.) and ceramic near5 substrate and mmic	USPAT	2003/10/28 10:55
-	25	((333/247).CCLS.) and ceramic near5 substrate and mmic and chip	USPAT	2003/10/28 11:28
-	1	("5852391").PN.	USPAT	2003/10/28 11:29
-	0	(("5852391").PN.) and capacitor and resistor	USPAT	2003/10/28 11:29
-	1	(("5852391").PN.) and capacitor	USPAT	2003/10/28 14:35
-	0	(("5982250").PN.) and capacitor and (resistor resistance)	USPAT	2003/10/28 14:35
-	1	("5982250").PN.	USPAT	2003/10/28 15:06
-	1	("5852391").PN.	USPAT	2003/10/28 16:09
-	1	("6175287").PN.	USPAT	2003/10/28 16:09

-	60	(US-6421012-\$ or US-6266015-\$ or US-5331123-\$ or US-6580931-\$ or US-6552696-\$ or US-6492952-\$ or US-6215454-\$ or US-6211824-\$ or US-6195047-\$ or US-6498551-\$ or US-6522868-\$ or US-6507110-\$ or US-6489679-\$ or US-6476463-\$ or US-6442374-\$ or US-6072991-\$ or US-6002375-\$ or US-5852391-\$ or US-6627992-\$ or US-6594479-\$ or US-5111199-\$ or US-5422783-\$ or US-5451818-\$ or US-5319329-\$ or US-5239685-\$ or US-5406122-\$).did. or (US-6175287-\$ or US-6278337-\$ or US-6278159-\$ or US-6268779-\$ or US-6424074-\$ or US-5545924-\$ or US-6257058-\$ or US-6201728-\$ or US-6124636-\$ or US-5898909-\$ or US-5423080-\$ or US-6124765-\$ or US-6073484-\$ or US-6441449-\$).did. or (US-20030117245-\$ or US-20030155651-\$ or US-20030148739-\$ or US-20020171141-\$ or US-20030034861-\$ or US-20030027530-\$ or US-20020132589-\$ or US-20030169134-\$ or US-20020030269-\$ or US-20020086655-\$ or US-20010001224-\$ or US-20020055349-\$ or US-20020030250-\$).did. or (US-5451818-\$ or US-5239685-\$ or WO-200223674-\$ or EP-712534-\$ or JP-11214578-\$ or EP-504020-\$ or WO-200075762-\$).did.	USPAT; US-PGPUB; DERWENT	2003/10/28 17:12
-	11	((US-6421012-\$ or US-6266015-\$ or US-5331123-\$ or US-6580931-\$ or US-6552696-\$ or US-6492952-\$ or US-6215454-\$ or US-6211824-\$ or US-6195047-\$ or US-6498551-\$ or US-6522868-\$ or US-6507110-\$ or US-6489679-\$ or US-6476463-\$ or US-6442374-\$ or US-6072991-\$ or US-6002375-\$ or US-5852391-\$ or US-6627992-\$ or US-6594479-\$ or US-5111199-\$ or US-5422783-\$ or US-5451818-\$ or US-5319329-\$ or US-5239685-\$ or US-5406122-\$).did. or (US-6175287-\$ or US-6278337-\$ or US-6278159-\$ or US-6268779-\$ or US-6424074-\$ or US-5545924-\$ or US-6257058-\$ or US-6201728-\$ or US-6124636-\$ or US-5898909-\$ or US-5423080-\$ or US-6124765-\$ or US-6073484-\$ or US-6441449-\$).did. or (US-20030117245-\$ or US-20030155651-\$ or US-20030148739-\$ or US-20020171141-\$ or US-20030034861-\$ or US-20030027530-\$ or US-20020132589-\$ or US-20030169134-\$ or US-20020030269-\$ or US-20020086655-\$ or US-20010001224-\$ or US-20020055349-\$ or US-20020030250-\$).did. or (US-5451818-\$ or US-5239685-\$ or WO-200223674-\$ or EP-712534-\$ or JP-11214578-\$ or EP-504020-\$ or WO-200075762-\$).did.) and (transfer adj tape lttt)	USPAT; US-PGPUB; DERWENT	2003/10/28 17:22
-	6	(transfer adj tape lttt) near6 ltcc	USPAT; US-PGPUB; DERWENT	2003/10/28 18:15
-	0	transfer adj tape adj lamination.ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 18:15

-	0	transfer adj tape adj lamination and low adj temperature adj2 ceramic	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 18:16
-	14	transfer adj tape and low adj temperature adj2 ceramic	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/28 18:24
-	1	("4645552").PN.	USPAT	2003/10/28 18:46
-	1	("4453142").PN.	USPAT	2003/10/28 19:02
-	1	("5982250").PN.	USPAT	2003/10/28 19:02
-	2	((5545924) or ("6124636")).PN.	USPAT	2003/10/29 09:00
-	0	("jp-5063346\$-\$ did.").PN.	USPAT; US-PPGPUB	2003/10/29 18:16
-	0	("jp-5063346\$-\$ did.").PN.	USPAT; US-PPGPUB; JPO	2003/10/29 18:17
-	0	("jp-5063346\$-\$ did.").PN.	USPAT; US-PPGPUB; JPO; DERWENT	2003/10/29 18:17
-	2	jp-05063346\$-\$ did.	USPAT; JPO; DERWENT	2003/10/29 18:21
-	2	jp-05199019\$-\$ did.	USPAT; JPO; DERWENT	2003/10/29 18:18
-	1	jp-61174693\$-\$ did.	USPAT; JPO; DERWENT	2003/10/29 18:22
-	2	jp-54135654\$-\$ did.	USPAT; JPO; DERWENT	2003/10/29 18:22
-	2	("5982250").PN.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 19:39
-	3	863030.ap.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 19:51
-	2219	((257/277) or (257/664) or (257/728) or (455/73) or (333/26) or (333/247)).CCLS.	USPAT; US-PPGPUB	2004/02/21 19:52
-	0	((257/277) or (257/664) or (257/728) or (455/73) or (333/26) or (333/247)).CCLS.) and transceiver.ti,ab,clm. and (low adj temperature adj co-fired adj ceramic ltcc).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 19:54
-	4	transceiver.ti,ab,clm. and (low adj temperature adj co-fired adj ceramic ltcc).ti,ab,clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 19:55
-	3	transceiver.ti,ab,clm. and (low adj temperature adj co-fired adj ceramic ltcc).ti,ab,clm. and (multi-layer multi adj layer multilayer)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 20:45
-	1	transceiver.ti,ab,clm. and (low adj temperature adj co-fired adj ceramic ltcc).ti,ab,clm. and (multi-layer multi adj layer multilayer) and ground and (mm millimeter)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/21 20:46